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Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





**SOD-123  
STPS0503Z**

## Description

Single Schottky rectifier suited for switch mode power supplies and high frequency DC to DC converters.

Packaged in SOD-123, this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications. Due to the small size of the package this device fits GSM and PCMCIA requirements.

**Table 1. Device summary**

$I_{F(AV)}$	0.5 A
$V_{RRM}$	30 V
$V_F(max)$	0.33 V

## Features

- Very small conduction losses
- Negligible switching losses
- Extremely fast switching

# 1 Characteristics

**Table 2. Absolute ratings (limiting values)**

Symbol	Parameter	Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage	30	V
$I_{F(RMS)}$	Forward rms current	2	A
$I_{F(AV)}$	Average forward current $\delta = 0.5$	$T_a = 55\text{ }^\circ\text{C}$	A
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10\text{ ms sinusoidal}$	A
$dV/dt$	Critical rate of rise of reverse voltage	10000	V/ $\mu\text{s}$
$T_{stg}$	Storage temperature range	-65 to +150	$^\circ\text{C}$
$T_j$	Operating junction temperature range <sup>(1)</sup>	-40 to +150	$^\circ\text{C}$
$T_L$	Maximum temperature for soldering during 10 s	260	$^\circ\text{C}$

1.  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  condition to avoid thermal runaway for a diode on its own heatsink

**Table 3. Thermal resistance**

Symbol	Parameter	Value	Unit
$R_{th(j-a)}$	Junction to ambient	340 <sup>(1)</sup>	$^\circ\text{C/W}$

1. Copper area on PCB  $S = 2.5\text{ mm}^2$

**Table 4. Static electrical characteristics**

Symbol	Parameter	Test conditions	Typ.	Max.	Unit	
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ }^\circ\text{C}$	$V_R = 15\text{ V}$		12	$\mu\text{A}$
		$T_j = 125\text{ }^\circ\text{C}$		3	5	mA
		$T_j = 25\text{ }^\circ\text{C}$	$V_R = V_{RRM}$		130	$\mu\text{A}$
		$T_j = 125\text{ }^\circ\text{C}$		9	21	mA
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ }^\circ\text{C}$	$I_F = 0.1\text{ A}$		0.375	V
		$T_j = 125\text{ }^\circ\text{C}$		0.20	0.22	
		$T_j = 25\text{ }^\circ\text{C}$	$I_F = 0.5\text{ A}$		0.43	
		$T_j = 125\text{ }^\circ\text{C}$		0.31	0.33	

1. Pulse test:  $t_p = 5\text{ ms}$ ,  $\delta < 2\%$

2. Pulse test:  $t_p = 380\text{ }\mu\text{s}$ ,  $\delta < 2\%$

To evaluate the maximum conduction losses use the following equation:

$$P = 0.23 \times I_{F(AV)} + 0.18 I_{F(RMS)}^2$$

Figure 1. Conduction losses versus average current

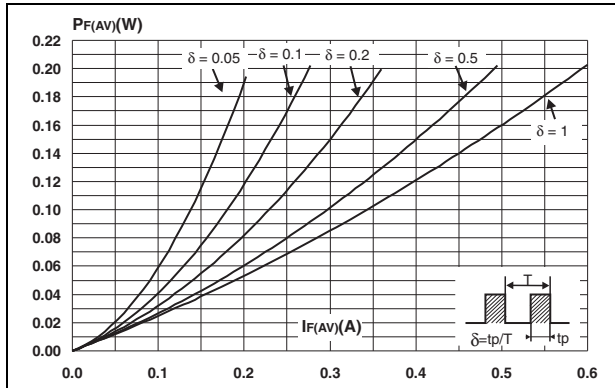


Figure 2. Average forward current versus ambient temperature ( $\delta = 0.5$ )

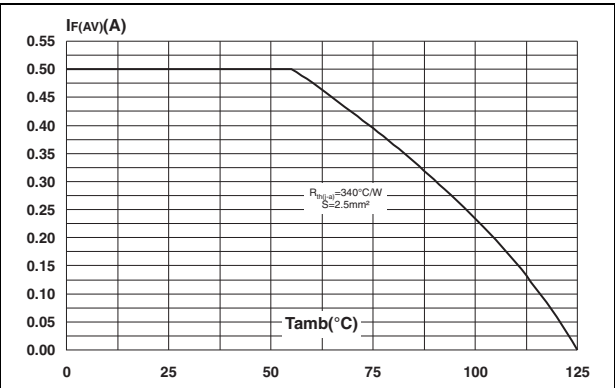


Figure 3. Non repetitive surge peak forward current versus overload duration (maximum values)

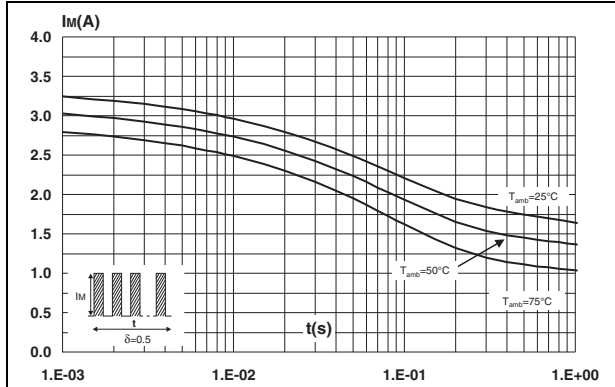


Figure 4. Relative variation of thermal impedance junction to ambient versus pulse duration

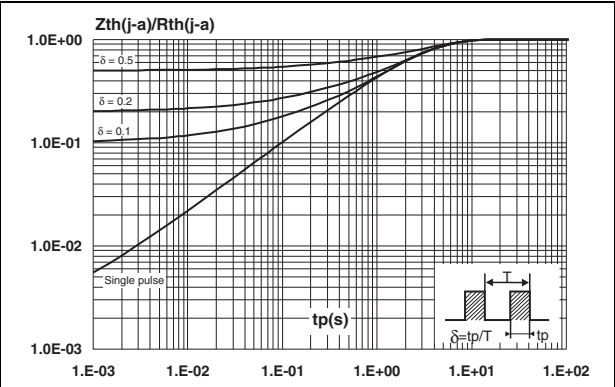


Figure 5. Reverse leakage current versus reverse voltage applied (typical values)

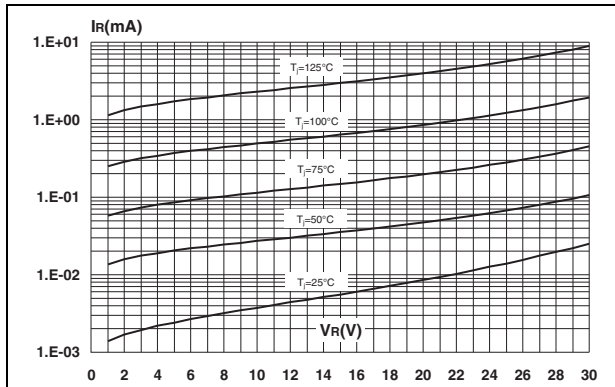


Figure 6. Reverse leakage current versus junction temperature (typical values)

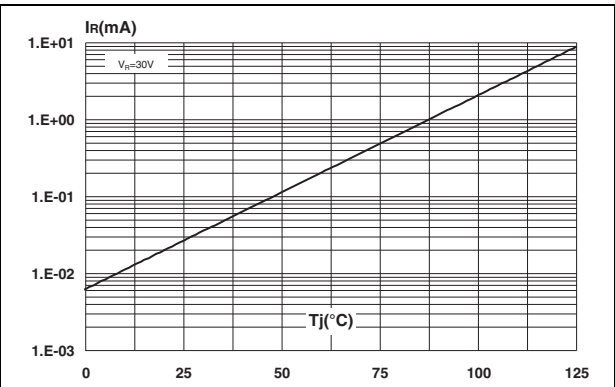


Figure 7. Junction capacitance versus reverse voltage applied (typical values)

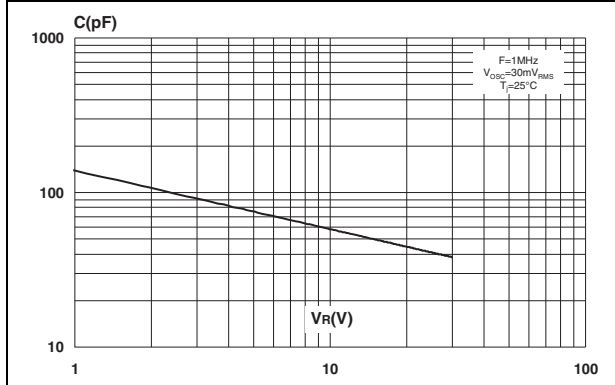


Figure 8. Forward voltage drop versus forward current

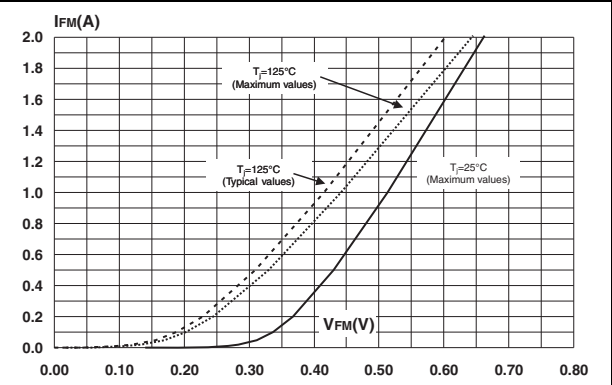
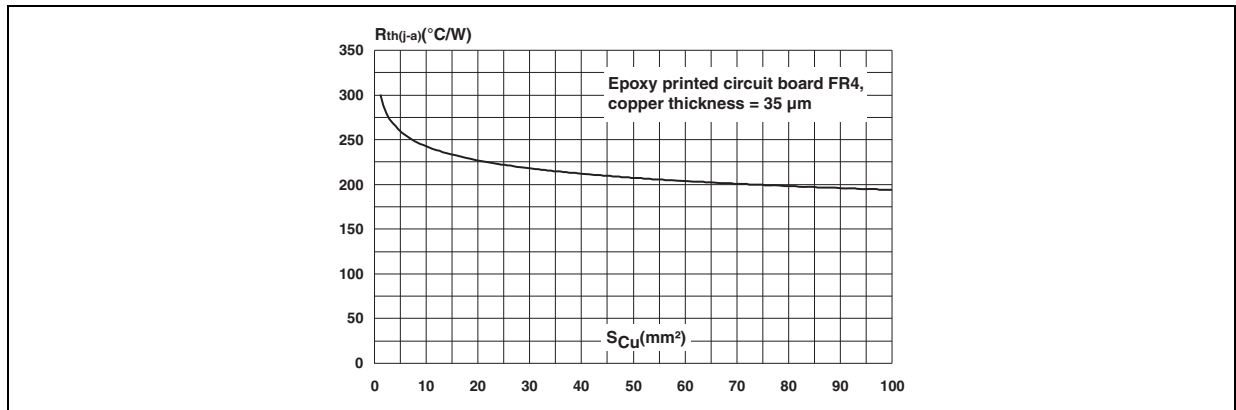


Figure 9. Thermal resistance junction to ambient versus copper surface under each lead (typical values)



## 2 Package information

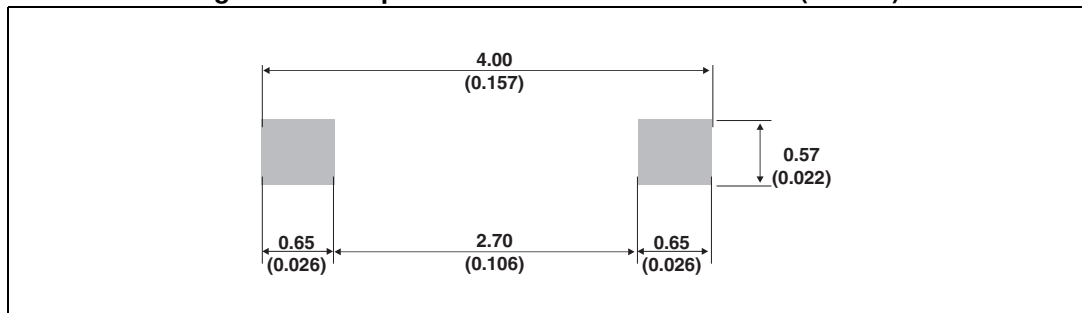
- Epoxy meets UL94, V0.
- Band indicates cathode.

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

**Table 5. SOD-123 dimensions**

Ref	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A		1.45		0.057
A1	0	0.1	0	0.004
A2	0.85	1.35	0.033	0.053
b	0.55 Typ.		0.022 Typ.	
c	0.15 Typ.		0.039 Typ.	
D	2.55	2.85	0.1	0.112
E	1.4	1.7	0.055	0.067
G	0.25		0.01	
H	3.55	3.75	0.14	0.1148

**Figure 10. Footprint - dimensions in millimeters (inches)**



### 3 Ordering information

**Table 6. Ordering information**

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS0530Z	Z53	SOD-123	0.01 g	3000	Tape and reel

### 4 Revision history

**Table 7. Document revision history**

Date	Revision	Changes
Mar-2003	1A	Initial release.
17-Oct-2006	2	Reformatted to current standards. Updated maximum junction temperatures to 150 °C and updated package illustration to show cathode bar on page 1
23-Apr-2014	3	Updated Tj max to Tj range in <a href="#">Table 2</a> .

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